TACFlux® 055

Introduction
TACFlux® 055 is an air reflow, halogen-free, no-clean flux used with Sn/Bi and Sn/Bi/Ag alloys. TACFlux® 055 provides excellent wetting in air and nitrogen and provides the low activation temperature necessary for the low melting Sn/Bi and Sn/Bi/Ag alloys.

Properties

<table>
<thead>
<tr>
<th>Test</th>
<th>Result</th>
</tr>
</thead>
<tbody>
<tr>
<td>Flux Type Classification</td>
<td>ROL0</td>
</tr>
<tr>
<td>Flux Induced Corrosion (Copper Mirror)</td>
<td>Pass</td>
</tr>
<tr>
<td>Presence of Halide: Silver Chromate</td>
<td>Pass</td>
</tr>
<tr>
<td>Fluoride Spot Test</td>
<td>Pass</td>
</tr>
<tr>
<td>Cl Equivalent</td>
<td>0%</td>
</tr>
<tr>
<td>SIR</td>
<td>Pass</td>
</tr>
<tr>
<td>Viscosity (C &amp; P)*</td>
<td>16.0 kcps</td>
</tr>
<tr>
<td>Tack</td>
<td>215 g</td>
</tr>
</tbody>
</table>

*Cone & Plate viscosity @ 5 minutes

Additional Test Results:
- Appearance: Light Yellow-Amber
- Maximum Reflow Temperature: 200°C
- Reflow Atmosphere: Nitrogen or Air
- Shelf Life: 1 year
- Storage Condition: Stored @ 0-30°C (tip down for syringe/cartridge)

Storage
TACFlux® 055 syringes and cartridges should be stored tip down at 0-30°C. If refrigerated, TACFlux® 055 should be thawed for 4 hours at room temperature before using.

Technical Support
Indium Corporation’s internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon and paste. Indium Corporation Technical Support engineers provide Rapid Response to all technical inquiries.

Material Safety Data Sheets
The MSDS for this product can be found online at http://www.indium.com/techlibrary/msds.php

Packaging
TACFlux® 055 is available in 10cc and 30cc syringes or 100g jars, however other packaging can be provided to meet specific requirements.

Cleaning
TACFlux® 055 is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner.

Reflow
Peak reflow temperature should be <200°C in an air or nitrogen atmosphere.

This product data sheet is provided for general information only. Not to be used as incoming product specifications.